

Amendment
U.S. Patent Application No. 10/829,362

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A device for cooling memory modules comprising:
a body comprising a comb-shaped configuration in longitudinal section and including a plurality of elements, the elements ~~thermal~~ thermally coupling at least two memory modules, wherein at least two adjacently aligned elements include surfaces that face each other, each surface including a contact element extending from and connected to the surface via a spring element that biases the contact element away from the surface, such that the contact elements extend toward and engage with a memory module that is placed between the adjacently aligned elements.
2. (Canceled)
3. (Currently Amended) The device as claimed in claim 1, ~~comprising:~~
a plurality of contact areas bearing in a planar manner wherein the contact elements include planar areas that contact a memory module inserted between the adjacently aligned elements.
4. (Canceled)
5. (Original) The device as claimed in claim 2, wherein the body is formed of aluminum.
6. (Currently Amended) The device as claimed in claim 5, wherein an insulation layer is formed at least partially on ~~the~~ a surface of ~~the~~ each contact ~~areas~~ element.

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7. (Currently Amended) The device as claimed in claim 2, wherein the body ~~has~~ includes cooling fins.

8. (Currently Amended) The device as claimed in claim 2, wherein the ~~basic~~ body ~~has~~ includes a fan as an active cooling element.

9. (Currently Amended) The device as claimed in claim 2, wherein the body ~~has~~ includes a Peltier element as an active cooling element.

10-11. (Canceled)